

*SPECIFICATION AMENDMENTS*

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Replace paragraph [0009] with:

a [0009] It is an object of the present invention to provide a method for effectively cleaning the substrate of a printing master without affecting the quality of the substrate, so that it can be reused in a next printing cycle without the appearance of ghost images. This object is realized by the method [of claim 1] for removing ink-accepting areas from a printing master by laser ablation, wherein the printing master comprises a substrate which comprises a support and a base layer, wherein the base layer contains a crosslinked hydrophilic binder and a metal oxide. Although applicable to other printing techniques such as letterpress printing, the method is especially suited for cleaning a lithographic printing master. [In a preferred embodiment, the cleaning method of claim 1 is used for recycling the substrate in an on-press coating and on-press exposure method as defined in claim 2. The method allows effective removal of ink-accepting areas from the substrate of the printing master (no ghost images in the subsequent printing cycle) without affecting the lithographic quality of the substrate, thereby allowing to use the same substrate in a large number of printing cycles of coating, exposing, printing and cleaning, said number being preferably larger than 5, more preferably larger than 10 and most preferably larger than 30.]

[ New paragraph [0010]: ]

[0010] In a preferred embodiment, the present invention discloses a method of lithographic printing with a reusable substrate by

- (a) providing a substrate comprising a support and a base layer which contains a crosslinked hydrophilic binder and a metal oxide;
- (b) applying one or more layer(s) on the base layer, thereby obtaining an imaging material;
- (c) making a printing master having ink-accepting areas by image-wise exposure of the imaging material to heat or light and optionally processing the imaging material;
- (d) printing;
- (e) removing the ink-accepting areas from the printing master by laser ablation; and
- (f) repeating steps (b) through (d).

This cleaning method is used for recycling the substrate in an on-press coating and on-press exposure method. The method allows effective removal of ink-accepting areas from the

A1  
(concluded)

substrate of the printing master (no ghost images in the subsequent printing cycle) without affecting the lithographic quality of the substrate, thereby allowing to use the same substrate in a large number of printing cycles of coating, exposing, printing and cleaning, said number being preferably larger than 5, more preferably larger than 10 and most preferably larger than 30.

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Replace original paragraph [0030] with:

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[0030] The imaging material used in the present invention can be exposed to heat or to light. The exposure is preferably carried out on-press, i.e. while the material is mounted on a press cylinder, preferably the plate cylinder that holds the printing master during printing. Exposure can be done by e.g. a thermal head, digitally modulated lamps, LEDs or a laser head. Preferably, one or more lasers such as a He/Ne laser, an Ar laser[s] or a violet laser diode are used. Most preferably, the light used for the exposure is not visible light so that daylight-stable materials can be used, e.g. a UV lamp or UV (laser) light or a laser emitting near infrared light having a wavelength in the range from about 700 to about 1500 nm is used, e.g. a semiconductor laser diode, a Nd:YAG or a Nd:YLF laser. The required laser power depends on the sensitivity of the image-recording layer, the pixel dwell time of the laser beam, which is determined by the spot diameter (typical value of modern plate-setters at  $1/e^2$  of maximum intensity : 10-25  $\mu\text{m}$ ), the scan speed and the resolution of the exposure apparatus (i.e. the number of addressable pixels per unit of linear distance, often expressed in dots per inch or dpi; typical value : 1000-4000 dpi). More technical details of on-press exposure apparatuses are described in e.g. U.S. Pat. 5,174,205 and U.S. Pat. 5,163,368.

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